

UVF High-pressure UV Lamp

Specification Datasheet · TopRays Special Light Sources

The UVF series is a high-power (2000 W) high-pressure UV discharge lamp of the medium / high-pressure mercury type, designed for industrial and professional applications that demand high UVA radiant output.



Main Parameters

Parameter	Value	Notes
Lamp power	2000 W	High-power industrial light source
Supply voltage	400 V	Compatible with three-phase industrial supplies
Lamp voltage	250 V	—
Lamp current	9 A	—

Spectral Performance

Parameter	Value	Notes
UVA radiant flux	490 W	Very high UVA output (315–400 nm) for efficient curing
UVB radiant flux	60 W	A small amount of UVB is emitted — use appropriate protection
Service life	750 hours	Matches the standard life of the HPA / HPM series

Highlight: UVA radiant flux of up to 490 W — nearly 25% of the 2000 W input — gives outstanding electrical-to-optical efficiency for high-speed curing or large-area exposure.

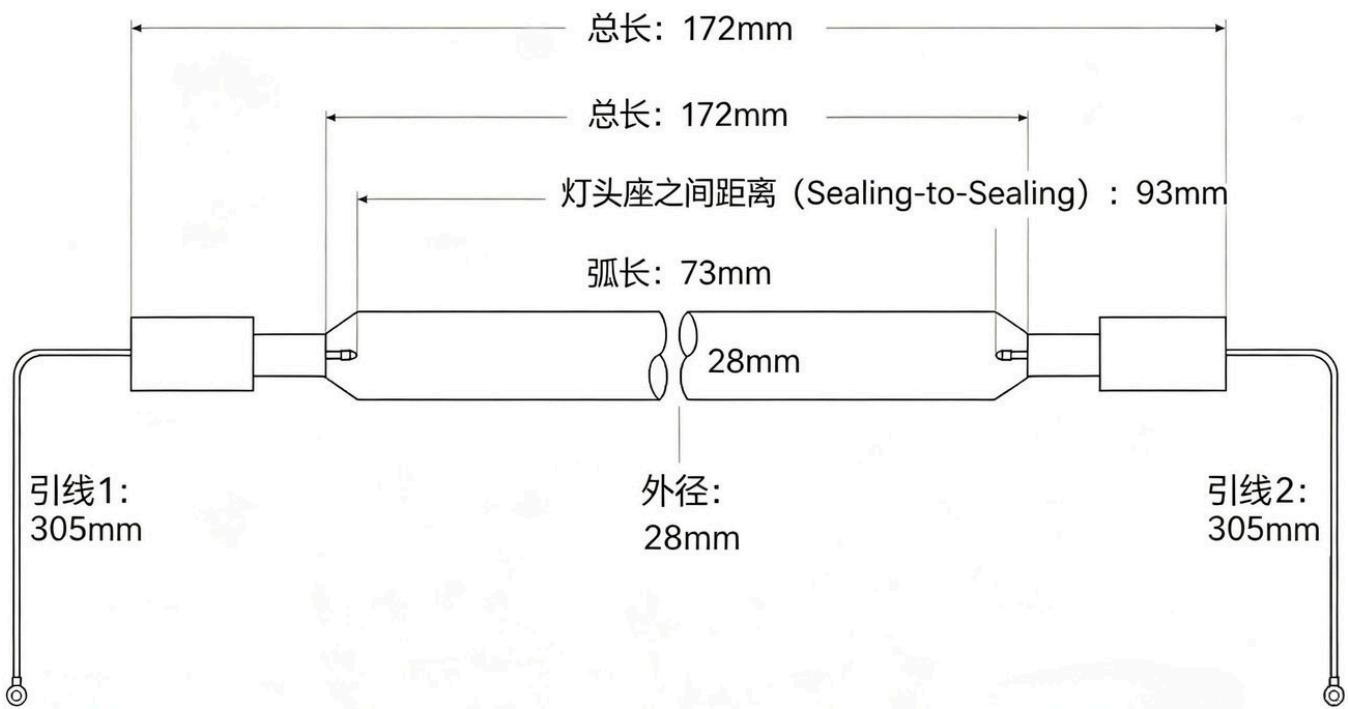
Operating Conditions

Parameter	Value	Notes
Burning position	Any position	Flexible mounting, free of horizontal / vertical restrictions (better than the horizontal-only HPA / HPM)
Minimum bulb temperature	650 °C	—
Maximum bulb temperature	950 °C	Same as the HPA / HPM series
Maximum pinch temperature	350 °C	Same as the HPA / HPM series
Ignition voltage	4.0 – 5.0 kV	Requires a matching igniter

Highlight: any burning position greatly increases flexibility in luminaire integration, whereas the HPA / HPM series normally require horizontal operation ($\pm 10^\circ$).

Dimensions

Parameter	Value
Overall length	172 mm
Electrode gap (arc length)	73 mm
Tube diameter	28 mm
Cable length	710 mm



UVF lamp outline dimensions (overall length 172 mm, arc length 73 mm, tube diameter 28 mm, lead 305 mm; in millimetres).

Applications

Application	Examples
Curing	Fast curing of inks, coatings and adhesives
Polymerization	Photo-initiated polymerization of plastics and resins
Material testing	Accelerated ageing / weathering tests
Medical engineering	Light therapy, disinfection, curing of medical devices
Electronics	PCB exposure, semiconductor manufacturing
Fluorescence	Mineral / material fluorescence inspection and research analysis